PCN	Nui	mber:		201	80619	002			PCN [	ate:	Ju	ıly :	3, 2018	
Title	<b>:</b> :	Datashee	for	CSE	86360	)Q5	D						•	
Cust	tome	er Contact	:	<b>PCN</b>	Manag	<u>jer</u>						De	pt:	Quality Services
Char	nge	Туре:												
Assembly Site						Design						Bump Site		
Assembly Process					Data Sheet				Щ		Bump Material			
Assembly Materials				Ļ	Part number change					<u>Ц</u>		Bump Process		
Mechanical Specification				<u> </u>	Test Site					<u> </u>		Fab Site		
Packing/Shipping/Labeling					Test Process					<u>H</u>		Fab Materials Fab Process		
Notific								atio	n Det	ails		Ш_	water	Tab Flocess
Notification Details  Description of Change:														
The product datasheet(s) is being updated as summarized below.  The following change history provides further details.  CSD86360Q5D  SLPS327B - SEPTEMBER 2012 - REVISED APRIL 2018  Changes from Revision A (May 2013) to Revision B  Changed Recommended PCB Design Overview section to Layout section 16														
• C	Updated Q5D Package Dimensions section													
		sheet num	oer v	will b	e char	ngin	g.	<u> </u>					01	
Device Family								nge Fr	om:			Change		
CSD86360Q5D							SLP	S327A				SLPS32	27B	
		anges may						heet	links p	rovide	d.			
http://www.ti.com/product/CSD86360Q5D														
		for Chang												
To accurately reflect device characteristics.														
Anti	cipa	ted impa	t or	ı Fit	, Form	ı, Fı	unctio	n, Qı	uality	or Rel	iabi	ility	/ (posi	tive / negative):
to th	e ac	tual device										nt o	nly. The	ere are no changes
Changes to product identification resulting from this PCN:														
None.														
Prod	duct	Affected:												
CSD86360Q5D									-	•				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com